

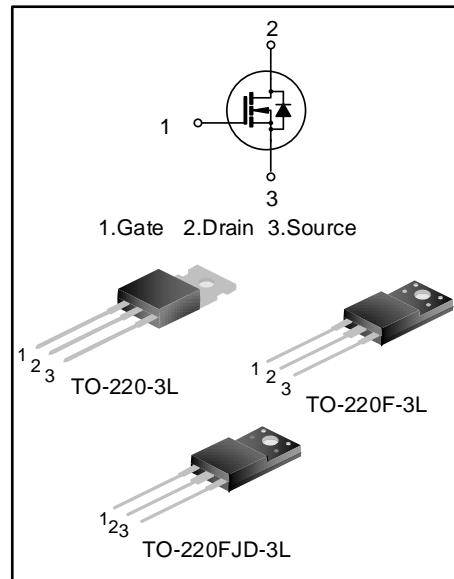
14A, 600V SUPER JUNCTION MOS POWER TRANSISTOR

DESCRIPTION

SVSP14N60F(FJD)(T)D2 is an N-channel enhancement mode high voltage power MOSFETs produced using Silan's super junction MOS technology. It achieves low conduction loss and switching losses. It leads the design engineers to their power converters with high efficiency, high power density, and superior thermal behavior. Furthermore, it's universal applicable, i.e., suitable for hard and soft switching topologies.

FEATURES

- 14A, 600V, $R_{DS(on)(typ.)}=0.25\Omega$ @ $V_{GS}=10V$
- New revolutionary high voltage technology
- Ultra low gate charge
- Periodic avalanche rated
- Extreme dv/dt rated
- High peak current capability



ORDERING INFORMATION

Part No.	Package	Marking	Hazardous Substance Control	Packing Type
SVSP14N60TD2	TO-220-3L	P14N60TD2	Halogen free	Tube
SVSP14N60FJDD2	TO-220FJD-3L	P14N60FJD	Halogen free	Tube
SVSP14N60FD2	TO-220F-3L	P14N60FD2	Halogen free	Tube



ABSOLUTE MAXIMUM RATINGS (UNLESS OTHERWISE NOTED, $T_J=25^\circ\text{C}$)

Characteristics	Symbol	Ratings		Unit
		SVSP14N60TD2	SVSP14N60F/FJDD2	
Drain-Source Voltage	V_{DS}	600		V
Gate-Source Voltage	V_{GS}	± 30		V
Drain Current	$T_C=25^\circ\text{C}$	I_D	14	A
	$T_C=100^\circ\text{C}$		8.8	
Drain Current Pulsed	I_{DM}	56		A
Power Dissipation ($T_C=25^\circ\text{C}$) -Derate above 25°C	P_D	120	38	W
		0.96	0.3	W/ $^\circ\text{C}$
Single Pulsed Avalanche Energy (Note 1)	E_{AS}	580		mJ
Reverse Diode dv/dt (Note 2)	dv/dt	15		V/ns
MOSFET dv/dt Ruggedness (Note 3)	dv/dt	50		V/ns
Operation Junction Temperature Range	T_J	$-55 \sim +150$		$^\circ\text{C}$
Storage Temperature Range	T_{stg}	$-55 \sim +150$		$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristics	Symbol	Value		Unit
		SVSP14N60TD2	SVSP14N60F/FJDD2	
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.04	3.29	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	62.5	$^\circ\text{C}/\text{W}$



ELECTRICAL CHARACTERISTICS (UNLESS OTHERWISE NOTED, $T_J=25^\circ\text{C}$)

Characteristics	Symbol	Test conditions		Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$		600	--	--	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=600\text{V}, V_{\text{GS}}=0\text{V}$		--	--	1.0	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 30\text{V}, V_{\text{DS}}=0\text{V}$		--	--	± 100	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$		2.0	--	4.0	V
Static Drain- Source on State Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V},$ $I_{\text{D}}=7.0\text{A}$	$T_J=25^\circ\text{C}$ $T_J=125^\circ\text{C}$	--	0.25	0.28	Ω
Gate Resistance	R_g	$f=1.0\text{MHz}$		--	3.0	--	
Input Capacitance	C_{iss}	$f=1\text{MHz}, V_{\text{GS}}=0\text{V},$ $V_{\text{DS}}=100\text{V}$		--	805	--	pF
Output Capacitance	C_{oss}			--	48	--	
Reverse Transfer Capacitance	C_{rss}			--	3.2	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=300\text{V}, V_{\text{GS}}=10\text{V}, R_{\text{G}}=24\Omega,$ $I_{\text{D}}=14\text{A}$		--	14	--	ns
Turn-on Rise Time	t_r			--	52	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$			--	117	--	
Turn-off Fall Time	t_f			--	43	--	
Total Gate Charge	Q_g	$V_{\text{DD}}=480\text{V}, V_{\text{GS}}=10\text{V},$ $I_{\text{D}}=14\text{A}$		--	26	--	nC
Gate-Source Charge	Q_{gs}			--	6.0	--	
Gate-Drain Charge	Q_{gd}			--	13	--	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

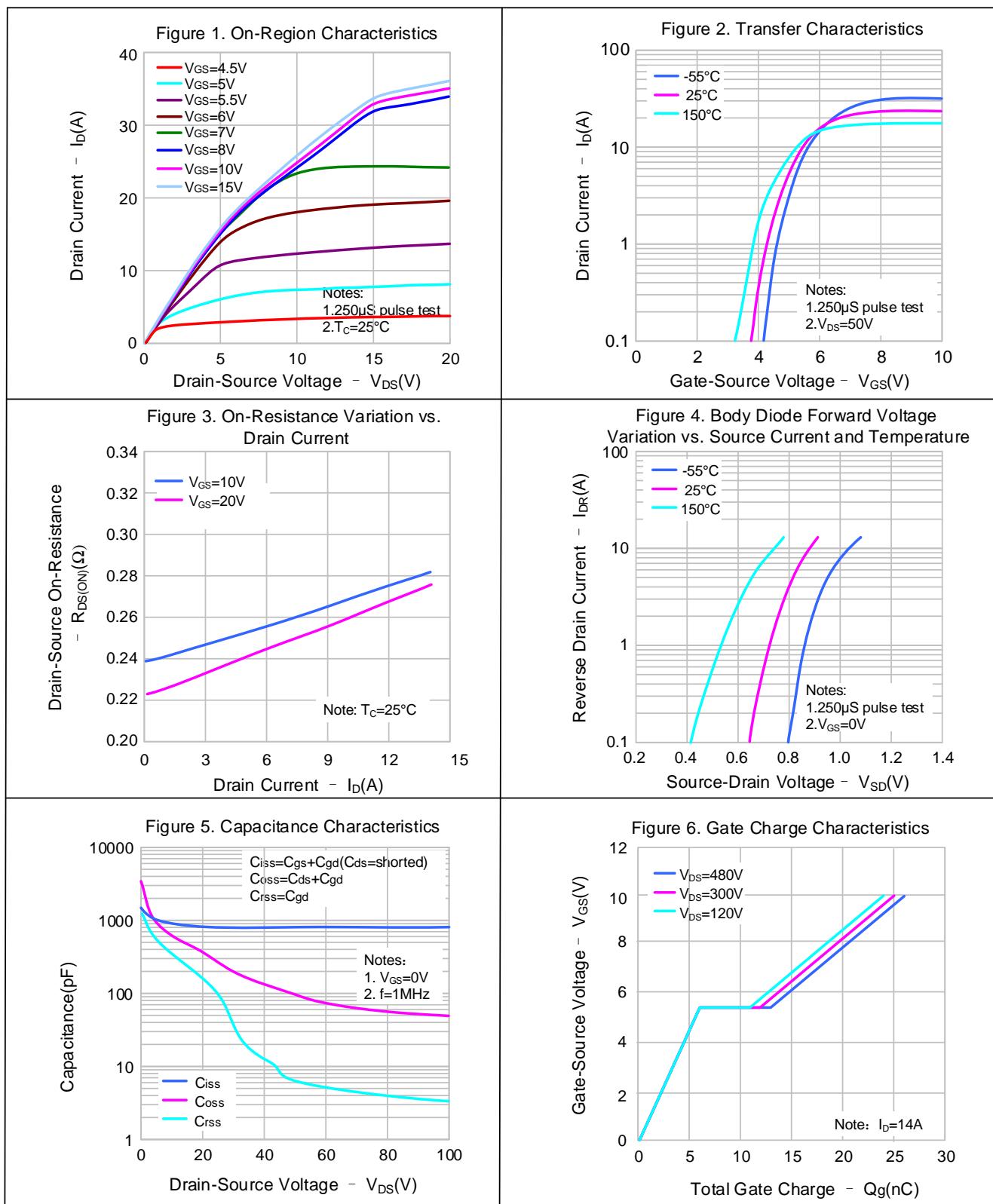
Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_s	Integral Reverse P-N Junction Diode in the MOSFET	--	--	14	A
Pulsed Source Current	I_{SM}		--	--	56	
Diode Forward Voltage	V_{SD}	$I_s=14\text{A}, V_{\text{GS}}=0\text{V}$	--	--	1.4	V
Reverse Recovery Time	T_{rr}	$V_{\text{DD}}=50\text{V}, I_F=14\text{A},$ $dI_F/dt=100\text{A}/\mu\text{s}$ (Note 4)	--	378	--	ns
Reverse Recovery Charge	Q_{rr}		--	4.6	--	μC

Notes:

1. $L=79\text{mH}, I_{\text{AS}}=3.5\text{A}, V_{\text{DD}}=100\text{V}, R_{\text{G}}=25\Omega$, starting temperature $T_J=25^\circ\text{C}$;
2. $V_{\text{DS}}=0\sim 400\text{V}, I_{\text{SD}} \leq 14\text{A}, T_J=25^\circ\text{C}$;
3. $V_{\text{DS}}=0\sim 480\text{V}$;
4. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$;
5. Essentially independent of operating temperature.

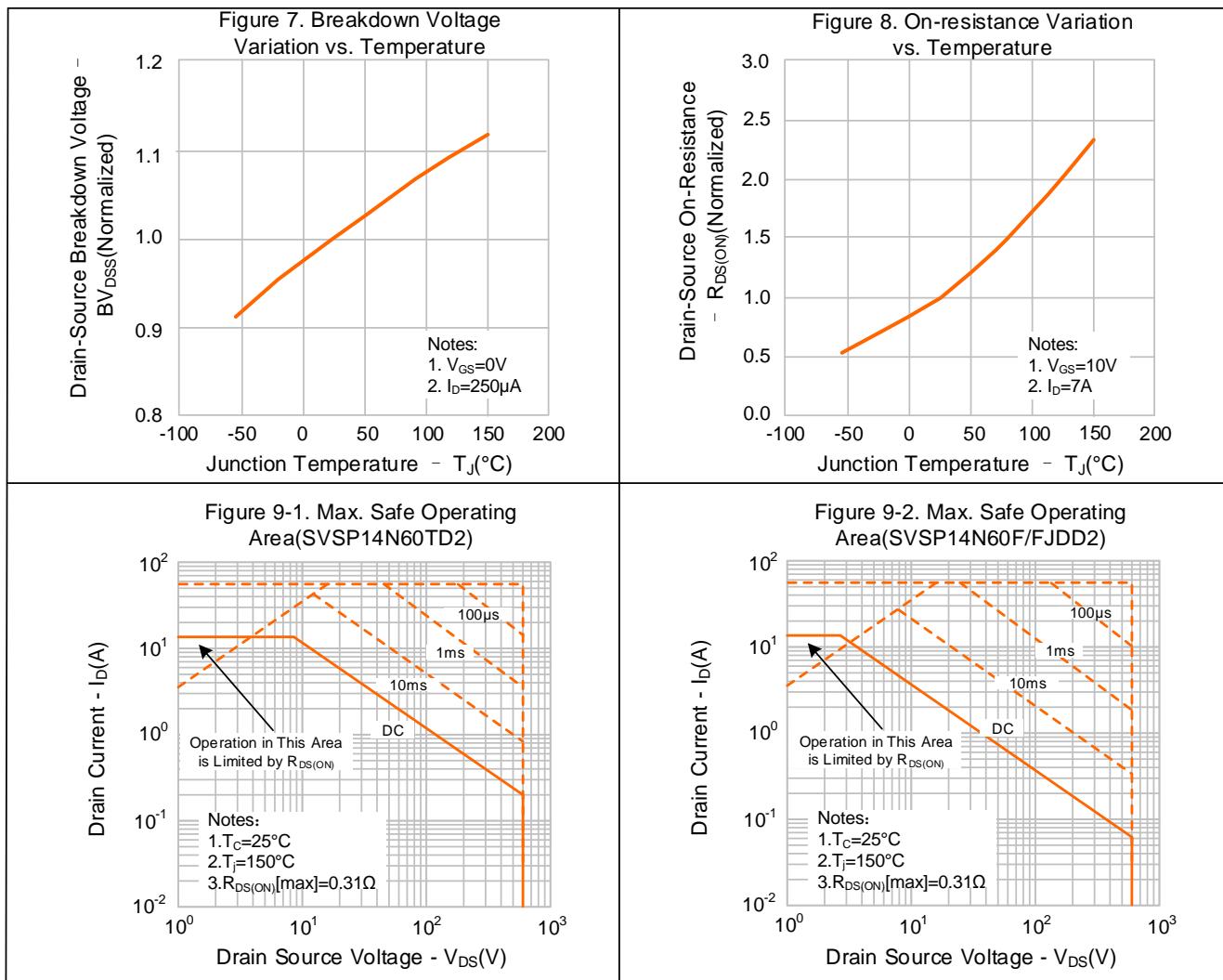


TYPICAL CHARACTERISTICS





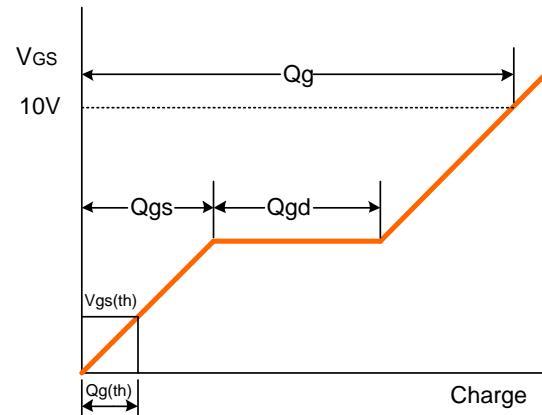
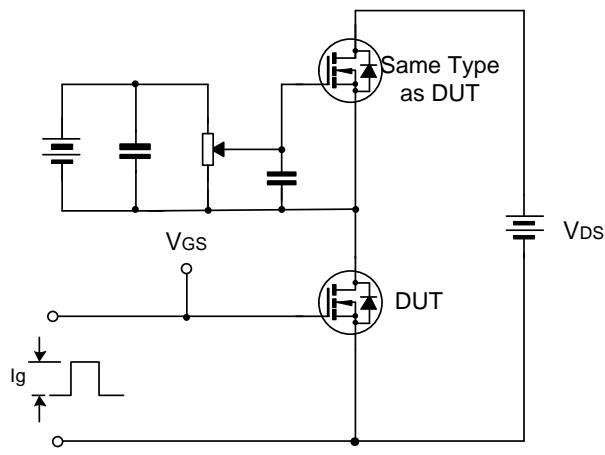
TYPICAL CHARACTERISTICS(CONTINUED)



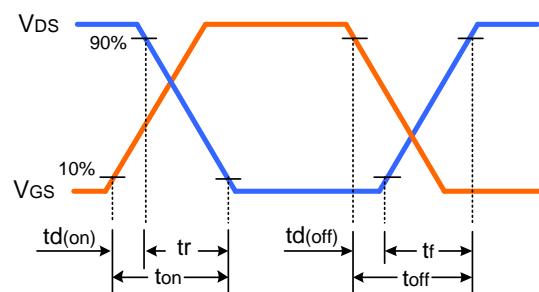
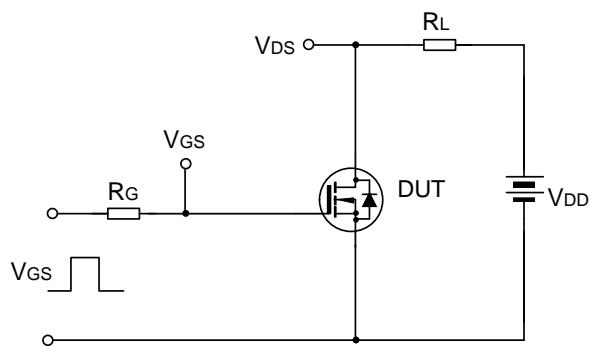


TYPICAL TEST CIRCUIT

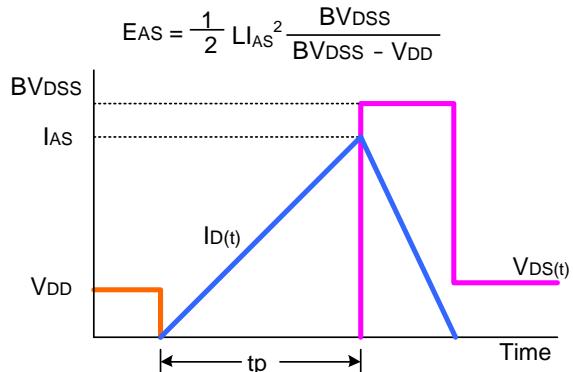
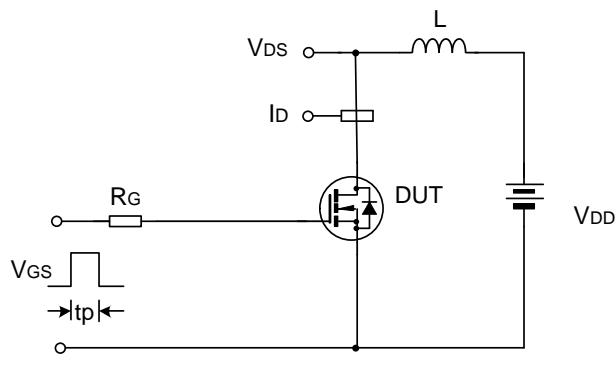
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveform

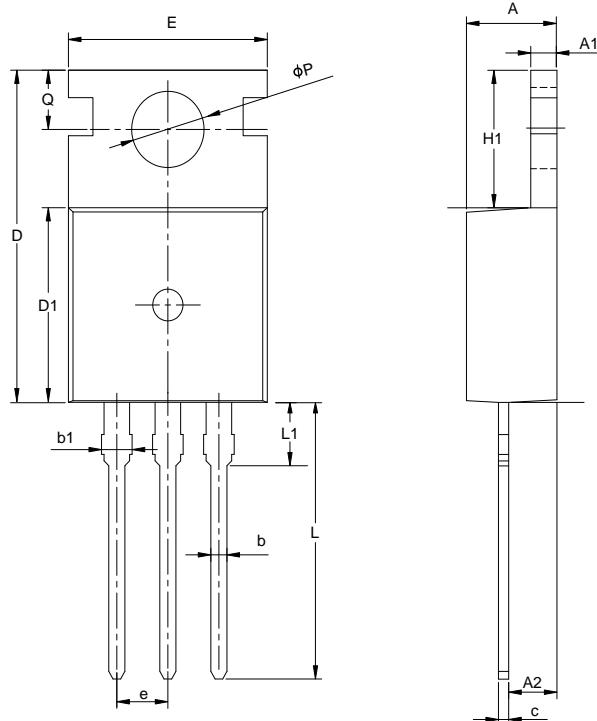




PACKAGE OUTLINE

TO-220-3L

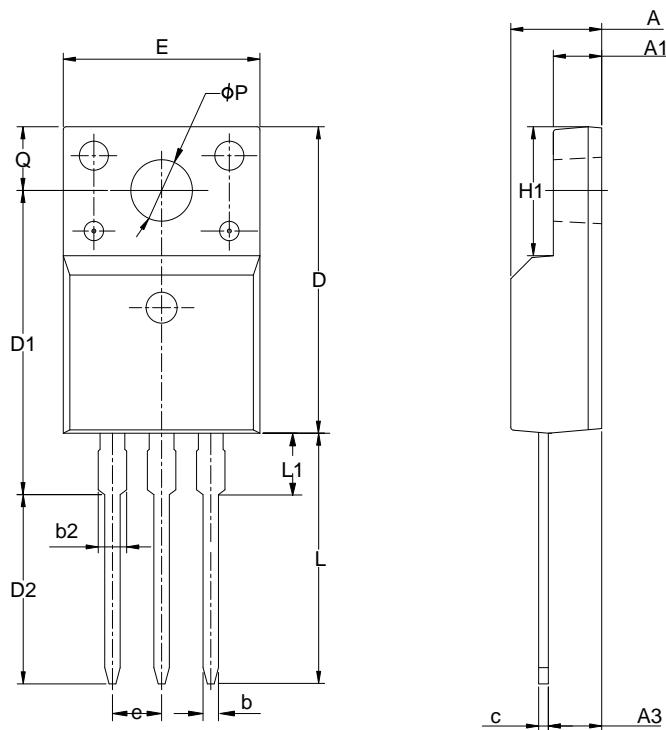
UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.30	4.50	4.70
A1	1.00	1.30	1.50
A2	1.80	2.40	2.80
b	0.60	0.80	1.00
b1	1.00	—	1.60
c	0.30	—	0.70
D	15.10	15.70	16.10
D1	8.10	9.20	10.00
E	9.60	9.90	10.40
e	2.54BSC		
H1	6.10	6.50	7.00
L	12.60	13.08	13.60
L1	—	—	3.95
φP	3.40	3.70	3.90
Q	2.60	—	3.20

TO-220FJD-3L

UNIT: mm



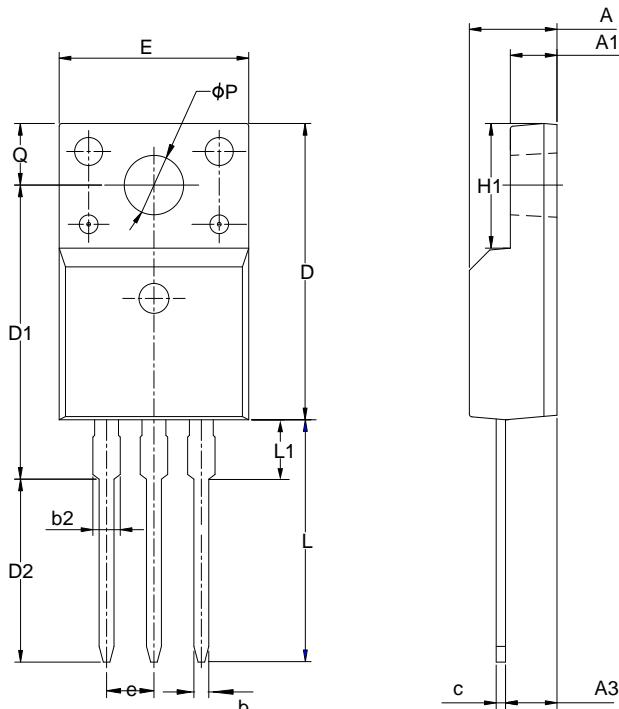
SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.42	4.70	5.02
A1	2.30	2.54	2.80
A3	2.50	2.76	3.10
b	0.55	0.70	0.85
b2	—	—	1.29
c	0.35	0.50	0.65
D	15.25	15.87	16.25
D1	13.97	14.47	14.97
D2	10.58	11.08	11.58
E	9.73	10.16	10.36
e	2.54BSC		
H1	6.40	6.68	7.00
L	12.48	12.98	13.48
L1	—	—	2.00
φP	3.00	3.18	3.40
Q	3.05	3.30	3.55



PACKAGE OUTLINE(CONTINUED)

TO-220F-3L

UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.42	4.70	5.02
A1	2.30	2.54	2.80
A3	2.50	2.76	3.10
b	0.70	0.80	0.90
b2	—	—	1.47
c	0.35	0.50	0.65
D	15.25	15.87	16.25
D1	15.30	15.75	16.30
D2	9.30	9.80	10.30
E	9.73	10.16	10.36
e	2.54BSC		
H1	6.40	6.68	7.00
L	12.48	12.98	13.48
L1	—	—	3.50
ϕP	3.00	3.18	3.40
Q	3.05	3.30	3.55

Important notice :

1. The instructions are subject to change without notice!
2. Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current. Please read the instructions carefully before using our products, including the circuit operation precautions.
3. Our products are consumer electronic products or the other civil electronic products.
4. When using our products, please do not exceed the maximum rating of the products, otherwise the reliability of the whole machine will be affected. There is a certain possibility of failure or malfunction of any semiconductor product under specific conditions. The buyer is responsible for complying with safety standards and taking safety measures when using our products for system design, sample and whole machine manufacturing, so as to avoid potential failure risk that may cause personal injury or property loss.
5. It is strongly recommended to identify the trademark when buying our products. Please contact us if there is any question.
6. Product promotion is endless, our company will wholeheartedly provide customers with better products!
7. Website: <http://www.silan.com.cn>



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Microelectronics

SVSP14N60F(FJD)(T)D2_Datasheet

Part No.: SVSP14N60F(FJD)(T)D2

Document Type: Datasheet

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Website: <http://www.silan.com.cn>

Rev.: 1.2

Revision History:

1. Update typical test circuit
 2. Update curve template
 3. Update package outline
 4. Update important notice
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Rev.: 1.1

Revision History:

1. Modify Electrical schematic and TYPICAL TEST CIRCUIT
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Rev.: 1.0

Revision History:

1. First release
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